

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c = 125$	I_o	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30	A
Typical Junction Capacitance ^{Note1}	C_j	30	pF
Typical Thermal Resistance ^{Note2}	R_{JA}	75	/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150	

Note:

- 1.Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

/ Electrical Characteristics(Ta=25)




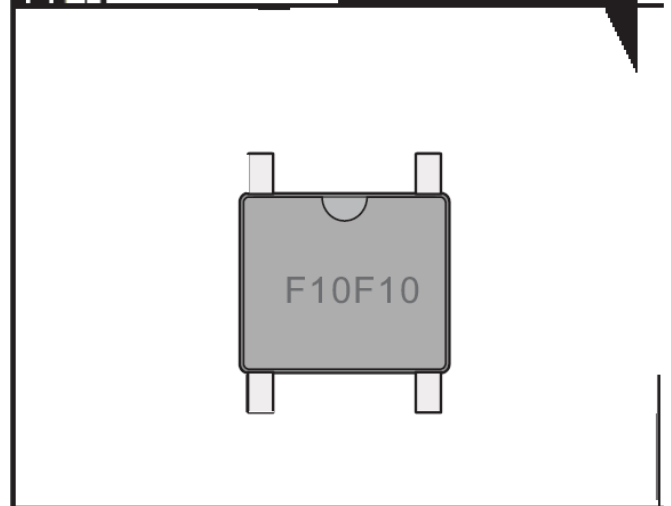
Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=1.0A$	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	μA
		$T_a=125$	50	μA
Maximum Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{rr}=0.25A$	200	ns

/ Electrical Characteristic Curve



/ Marking Instructions

Marking

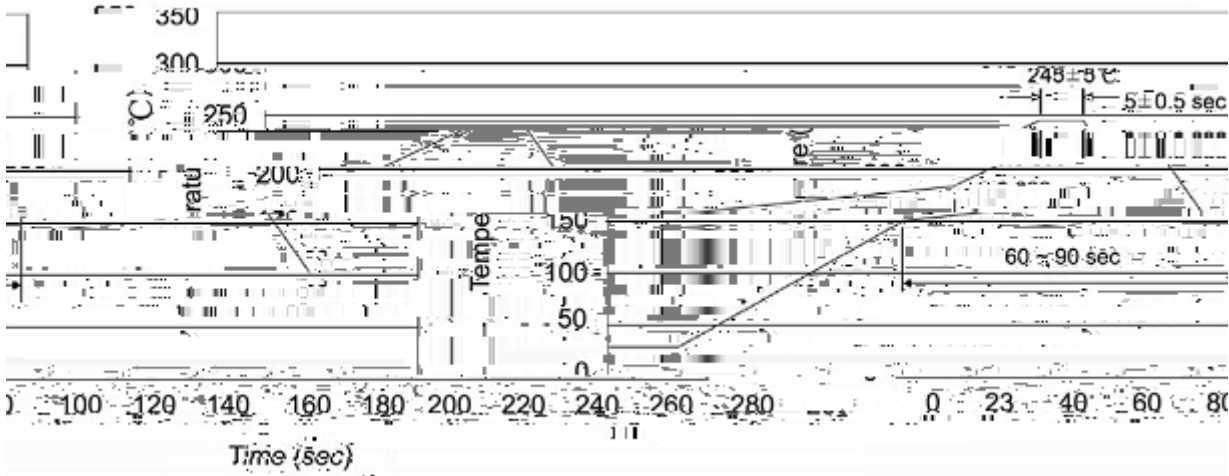
Marking code	Type number	Marking
		
		

/ Marking Instructions

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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-------|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
ABF	5000	2	10000	5	50000	13 x15	336X336X40	380X335X366

/ Notices